

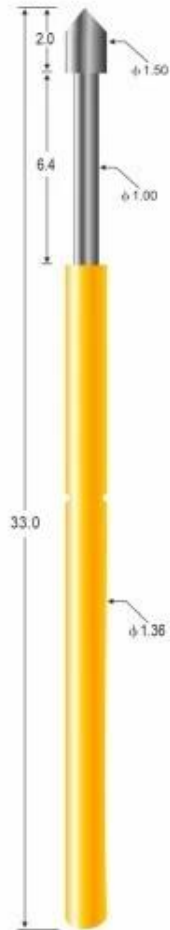


SFENG 1984 公司 (PCB 板) 提供



品名	SF-P100
尺寸	1.90mm x .0748"
厚度	厚度: 1.35mm (.0532") 厚度: 1.40mm (.0551")
重量	6.3 x .2481
重量	120g
材料	Cu/Rh 材料
电压	3A
电阻	50mΩ
MOQ	100
备注	7



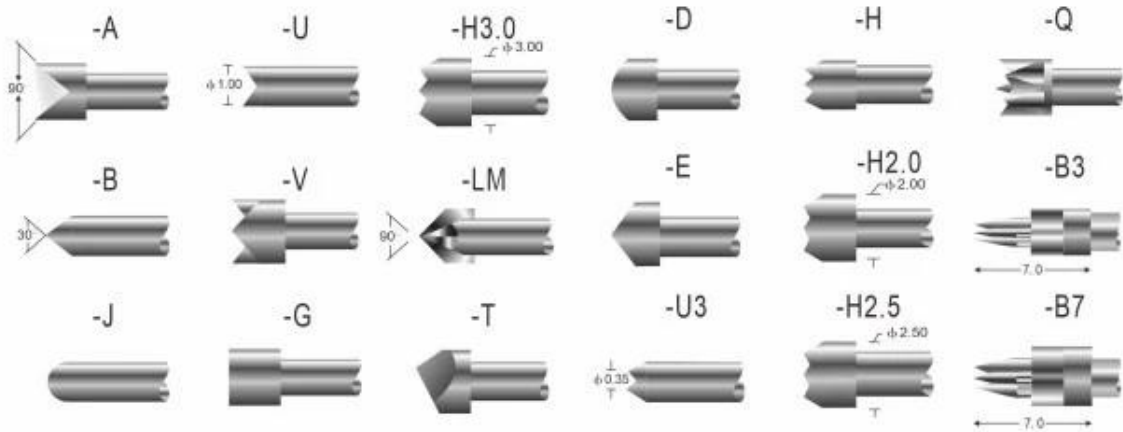


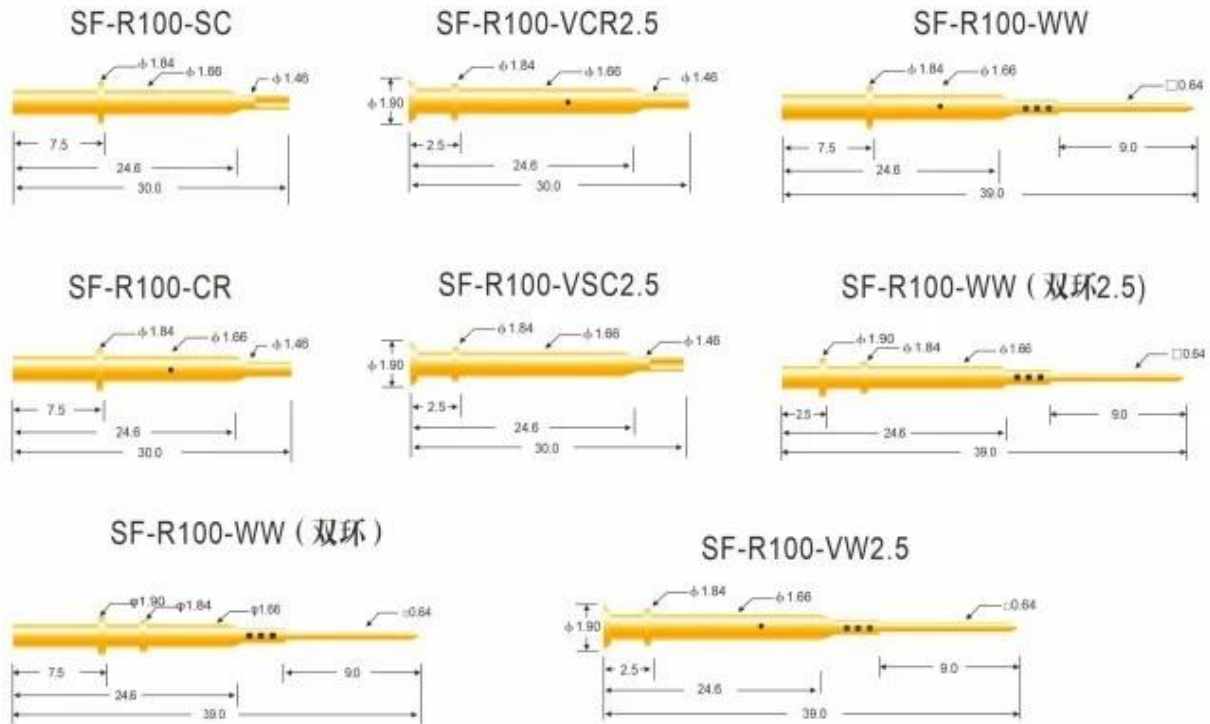
SF-P100-E

技术规格 PROBE SPECIFICATIONS

Recommended minimum center 最小间距	1.90mm(.0748 ")
Mounting hole size 钻孔尺寸	压克力: 1.35mm(.0532 ") 电木板、玻璃纤维板: 1.40mm(.0551 ")
Full travel 行程	6.3(.2481 ")
Spring force 弹簧压力	120g(克)
Materials and finishes 材料及涂饰	Plunger:SK4, Ni or Au plated BeCu, Ni or Au plated Phosphor bronze, Ni or Au plated Barrel:Phosphor bronze, Au plated Spring:Stainless steel
Current ration 额定电流	3A(安培)
Contact resistance 接触电阻	50mΩ(毫欧姆)

Receptacle specifications
Materials and finishes: Phosphor bronze,Gold plated





技术规格 PROBE SPECIFICATIONS

Recommended minimum center 最小间距	2.54mm(.1000 ")
Mounting hole size 钻孔尺寸	压克力: 1.70mm(.0670 ") 电木板、玻璃纤维板: 1.75mm(.0689 ")
Materials and finishes 材料及涂饰	Barrel: Brass, Gold plated
Connections 接线形式	Crimp: R100-VCR2.5, R100-CR Solder cup: R100-VSC2.5, R100-SC Wire wrap: R100-VW2.5, R100-WW, R100-WW(双环2.5), R100-WW(双环)

Receptacle specifications
Materials and finishes: Phosphor bronze, Gold plated



1. 24-pin probe
2. OEM probe
3. Probe
4. Probe



1. PCB ICT FCT
2. 2
3. BGA
4. QZ VZ LM
- 5.
- 6.
7. 30# OK POM



1. Raw material warehouse



2. Lathe workshop



3. Assemble workshop



4. Quality inspection



5. Finished products



6. Packing



